



Title of Change:	FOD819 datasheet update	
Effective date:	26 June 2018	
Contact information:	Contact your local ON Semiconductor Sales Office or <chingaik.yeoh@onsemi.com>	
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.	
Change Category:	<input type="checkbox"/> Wafer Fab <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input checked="" type="checkbox"/> Other <u>DATASHEET</u>	
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Addition <input type="checkbox"/> Material Change <input checked="" type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____	
Sites Affected:	ON Semiconductor Sites: None	External Foundry/Subcon Sites: None
Description and Purpose:		
Update FOD819 datasheet specs : - The Storage temp, Operating temp and Junction temp from -40degC to -55degC. - Revise the BVCEO from 40V to 80V. Improving the product existing specification and performance, so the change will not impact the customer applications. The update in datasheet will not impact form, fit, or function of product(s).		
List of Affected Parts:		
FOD819 FOD819S FOD819SD		

Appendix A: Changed Products

Product	Customer Part Number
FOD819	
FOD819S	
FOD819SD	